L Number	Hits	Search Text	DB	Time stamp
2	0	((photoinitiator or photopolymer or photopolymerizable) near (electrode or pad or terminal)) and (chip or die)	USPAT; US-PGPUB; EPO; JPO;	2003/06/24 14:30
1	21	(photoinitiator or photopolymer or photopolymerizable) near (electrode or pad or terminal)	DERWENT; IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/24 14:35
3	14	257/778.ccls. and (photoinitiator or photopolymer or photopolymerizable)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/24 17:19
4	1	6331736.URPN.	IBM_TDB USPAT	2003/06/24
5	28	("3461357"   "3809625"   "3881971"   "4808552"   "4988423"   "5106461"   "5130768"   "5231590"   "5244837"   "5341310"   "5414637"   "5495397"   "5506172"   "5523253"   "5523626"   "5534465"   "5570504"   "5597470"   "5619017"   "5632631"   "5640761"   "5666007"   "5679609"   "5688721"   "5751031"   "5904556"   "6078100"	USPAT	2003/06/24 14:49
8	1964	"6175161").PN. (circuit adj (substrate or board)) and (photoinitiator or photopolymer or photopolymerizable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/24 15:02
9	306	(circuit adj (substrate or board)) with (photoinitiator or photopolymer or photopolymerizable)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/24 15:05
10	293	((circuit adj (substrate or board)) with (photoinitiator or photopolymer or photopolymerizable) ) and (@ad<20010718)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/24 17:43
11	34	(((circuit adj (substrate or board)) with (photoinitiator or photopolymer or photopolymerizable)) and (@ad<20010718)) and ((terminal or pad or electrode) with (photoinitiator or photopolymer or photopolymerizable))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/06/24 17:21
12	48	257/778.ccls. and ((resin and (pad or terminal or electrode)) with ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/06/24 15:48
13	580	257/778.ccls. and (circuit adj (board or substrate)) and ball	USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/24 15:50
14	160	(257/778.ccls. and (circuit adj (board or substrate)) and ball) and underfill	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/24 15:51
15	131	((257/778.ccls. and (circuit adj (board or substrate)) and ball) and underfill) and (@ad<20010718)	IBM_TDB USPAT; US-PGPUB; EPO; JPO; DERWENT;	2003/06/24 16:34
16	1	("5903056").PN.	IBM_TDB USPAT	2003/06/24 16:34

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17	152	(bake or baking) near (photoinitiator or	USPAT;	2003/06/24
1		photopolymer or photopolymerizable or	US-PGPUB;	17:51
		polymer)	EPO; JPO;	
			DERWENT;	
	1		IBM TDB	
18	125	((bake or baking) near (photoinitiator or	USPAT;	2003/06/24
1.0	1.00	photopolymer or photopolymerizable or	US-PGPUB;	17:21
	1	polymer) ) and (@ad<20010718)	EPO; JPO;	17.21
		polymer, , and (gad 20010/18)		
	Ì		DERWENT;	
10			IBM_TDB	1
19	37	(((bake or baking) near (photoinitiator	USPAT;	2003/06/24
		or photopolymer or photopolymerizable or	US-PGPUB;	17:23
1	1	polymer) ) and (@ad<20010718)) and	EPO; JPO;	İ
	1	(terminal or pad or electrode)	DERWENT;	
	li .		IBM TDB	
20	0	((bake or baking) with (terminal or	USPAT;	2003/06/24
	1	electrode or pad)) near (photoinitiator	US-PGPUB;	17:42
		or photopolymer or photopolymerizable or	EPO; JPO;	- / •
Į.	1	polymer)	DERWENT;	
		polymer)	IBM TDB	
2.1	483			2002/06/24
21	483	((bake or baking) with (terminal or	USPAT;	2003/06/24
		electrode or pad)) and (photoinitiator or	US-PGPUB;	17:43
		photopolymer or photopolymerizable or	EPO; JPO;	
		polymer)	DERWENT;	
			IBM TDB	
22	171	(((bake or baking) with (terminal or	USPAT;	2003/06/24
		electrode or pad)) and (photoinitiator or	US-PGPUB;	17:43
1		photopolymer or photopolymerizable or	EPO; JPO;	
		polymer) ) and ((terminal or electrode or	DERWENT;	
		pad) with (photoinitiator or photopolymer	IBM TDB	
1	1	or photopolymerizable or polymer))	1011-100	
23	143		TICDAM.	2003/06/24
23	143	1	USPAT;	
}	}	electrode or pad)) and (photoinitiator or	US-PGPUB;	17:44
		photopolymer or photopolymerizable or	EPO; JPO;	
		polymer) ) and ((terminal or electrode or	DERWENT;	
\		pad) with (photoinitiator or photopolymer	IBM_TDB	
		or photopolymerizable or polymer)) ) and		
	!	(@ad<20010718)		
24	20	((((bake or baking) with (terminal or	USPAT;	2003/06/24
		electrode or pad)) and (photoinitiator or	US-PGPUB;	17:45
		photopolymer or photopolymerizable or	EPO; JPO;	
1		polymer) ) and ((terminal or electrode or	DERWENT;	ì
		pad) with (photoinitiator or photopolymer	IBM TDB	
l	İ	or photopolymerizable or polymer))) and	1011_100	
				1
		(@ad<20010718)) and ((chip or die or		
1 0 5		semiconductor) and (board or substrate))		0000/06/04
25	0	((bake or baking) and (warp or warping or	USPAT;	2003/06/24
1		bend or bending)) near (photoinitiator or	US-PGPUB;	17:52
1	i i	photopolymer or photopolymerizable or	EPO; JPO;	
		polymer)	DERWENT;	
			IBM TDB	
26	175	(warp or warping or bend or bending)	USPAT;	2003/06/24
!		with ((photoinitiator or photopolymer or	US-PGPUB;	17:53
]		photopolymerizable or polymer) and	EPO; JPO;	
1		(electrode or pad or terminal))	DERWENT;	
1		(ofcorrode of pad of terminal)		
L	<u> </u>	1	IBM TDB	